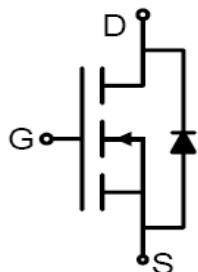
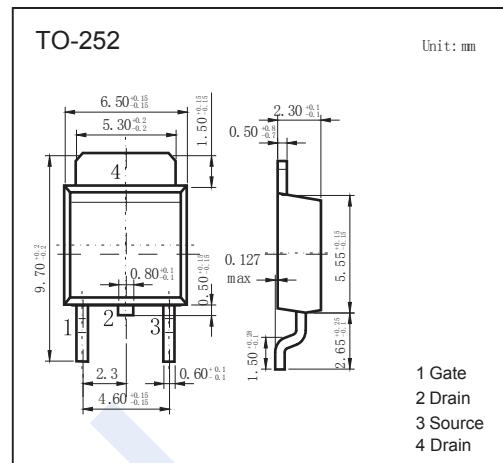


N-Channel MOSFET

NDT90N03

■ Features

- V_{DS} (V) = 30V
 - I_D = 85 A (V_{GS} = 10V)
 - $R_{DS(ON)} < 5m\Omega$ (V_{GS} = 10V)
 - $R_{DS(ON)} < 8m\Omega$ (V_{GS} = 4.5V)
 - High Power and current handing capability
 - Lead free product is acquired
 - Surface Mount Package



■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit	
Drain-Source Voltage	V _{DS}	30	V	
Gate-Source Voltage	V _{GS}	±20		
Continuous Drain Current	T _c =25°C	I _D	A	
	T _c =70°C			
Pulsed Drain Current		I _{DM}	200	
Power Dissipation	T _c =25°C	P _D	W	
	T _c =70°C			
Repetitive Avalanche Energy (Note.1)	E _{AS}	110	mJ	
Thermal Resistance.Junction- to-Case	R _{thJC}	2	°C/W	
Junction Temperature	T _J	175	°C	
Storage Temperature Range	T _{stg}	-55 to 175		

Note.1:EAs condition: $T_J=25^{\circ}\text{C}$, $V_{DD}=20\text{V}$, $V_G=10\text{V}$, $R_G=25\Omega$

N-Channel MOSFET

NDT90N03

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V _{DSS}	I _D =250 μA, V _{GS} =0V	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V			1	μA
Gate-Body Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250 μA	1.2		2.4	V
Static Drain-Source On-Resistance	R _{Ds(on)}	V _{GS} =10V, I _D =20A T _c =25°C		5		mΩ
		V _{GS} =10V, I _D =20A T _c =125°C			6.8	
		V _{GS} =4.5V, I _D =20A			8	
Forward Transconductance	g _F	V _{DS} =5V, I _D =20A	50			S
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =15V, f=1MHz		2100		pF
Output Capacitance	C _{oss}			500		
Reverse Transfer Capacitance	C _{rss}			200		
Gate Resistance	R _g	V _{GS} =0V, V _{DS} =0V, f=1MHz		1.7		Ω
Total Gate Charge (10V)	Q _g	V _{GS} =10V, V _{DS} =15V, I _D =20A		18		nC
Total Gate Charge (4.5V)	Q _g			8.5		
Gate Source Charge	Q _{gs}			4.8		
Gate Drain Charge	Q _{gd}			2.5		
Turn-On DelayTime	t _{d(on)}	V _{GS} =10V, V _{DS} =15V, R _L =0.75Ω, R _{GEN} =3Ω		7.5		ns
Turn-On Rise Time	t _r			4.8		
Turn-Off DelayTime	t _{d(off)}			23		
Turn-Off Fall Time	t _f			4.5		
Body Diode Reverse Recovery Time	t _{rr}	I _F = 20A, dI/dt= 100A/us		14		nC
Body Diode Reverse Recovery Charge	Q _{rr}			16		
Maximum Body-Diode Continuous Current	I _s				85	A
Diode Forward Voltage	V _{SD}	I _s =20A, V _{GS} =0V			1.2	V

■ Marking

Marking	CSD30N39
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N-Channel MOSFET

NDT90N03

■ Typical Characteristics

Figure1. Power Dissipation

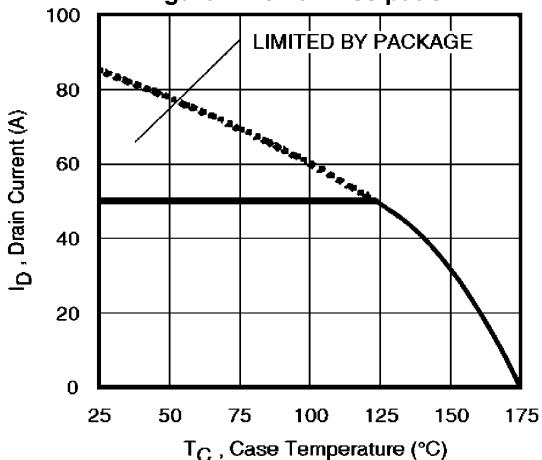


Figure2. Drain Current

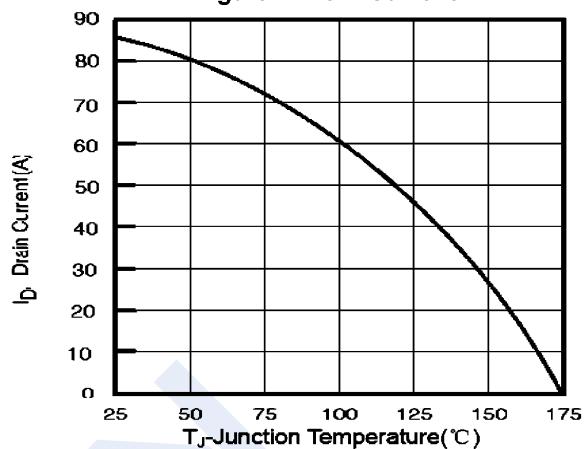


Figure3. Output Characteristics

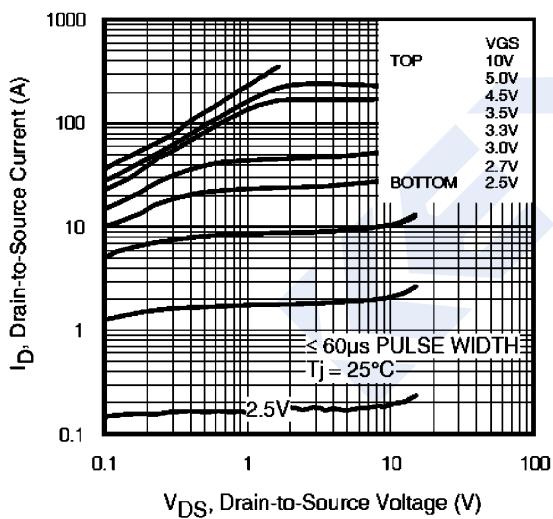


Figure4. Transfer Characteristics

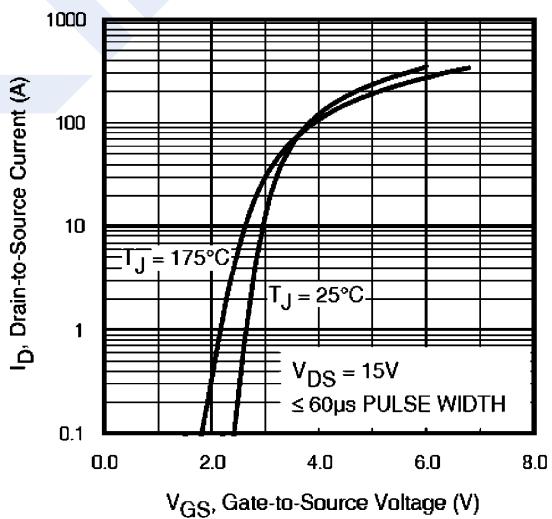


Figure5. Capacitance

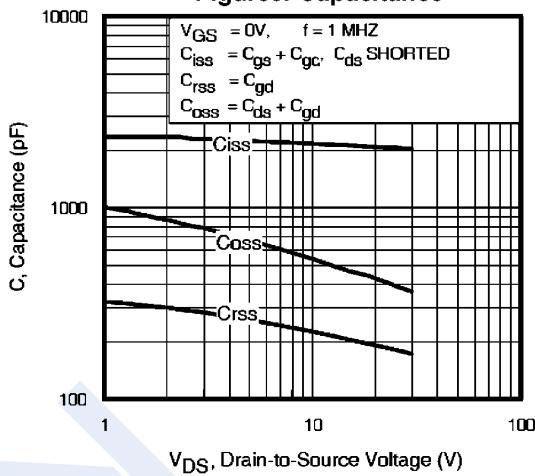
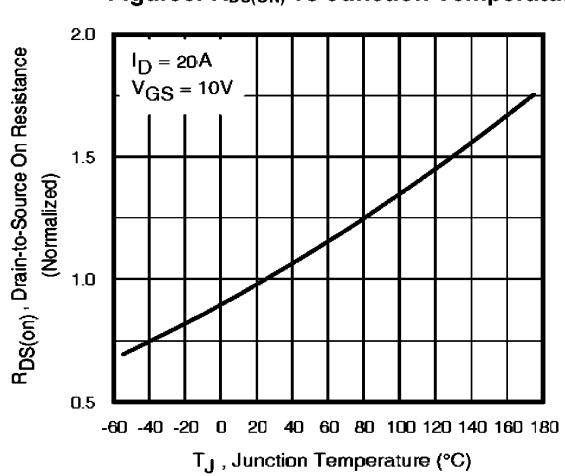


Figure6. $R_{DS(on)}$ vs Junction Temperature



N-Channel MOSFET

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■ Typical Characteristics

Figure 7. Max BV_{DSS} vs Junction Temperature

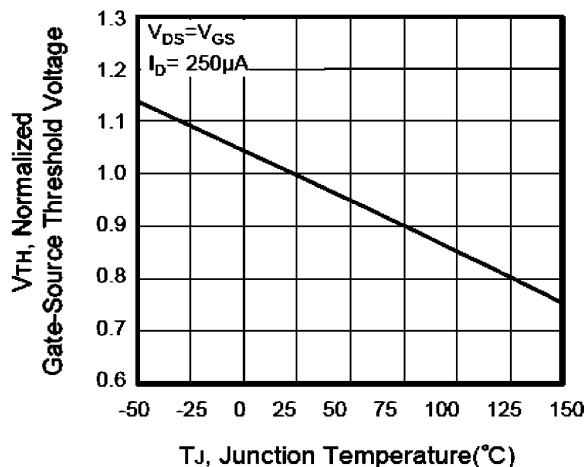


Figure 8. $V_{GS(th)}$ vs Junction Temperature

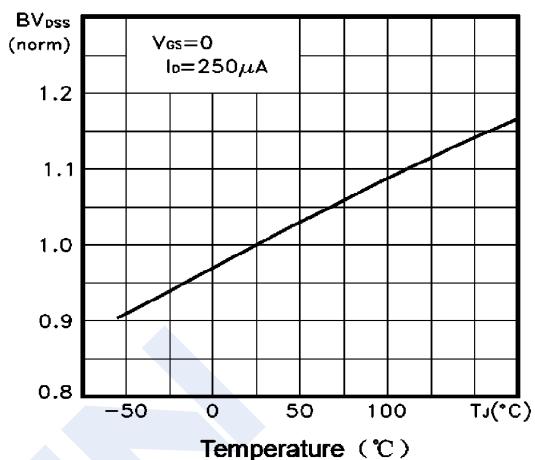


Figure 9. Gate Charge Waveforms

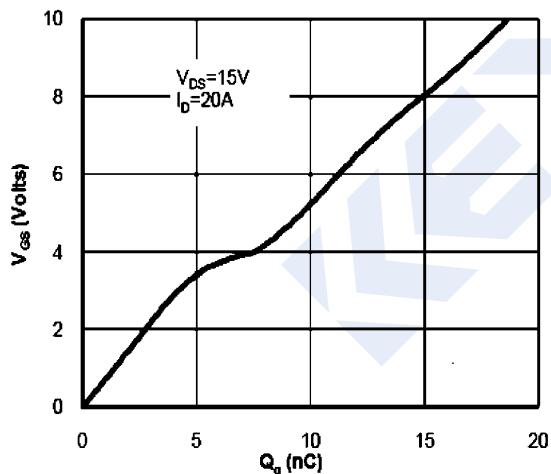


Figure 10. Maximum Safe Operating Area

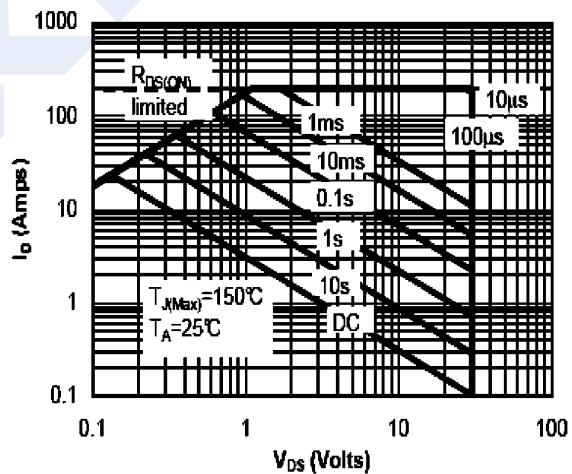


Figure 11. Normalized Maximum Transient Thermal Impedance

